



PMV164NEA

60 V, N-channel Trench MOSFET

7 May 2019

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Extended temperature range $T_j = 175 \text{ }^\circ\text{C}$
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 2 kV HBM (class H2)
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

4. Quick reference data

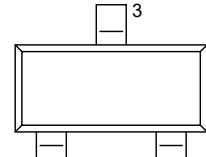
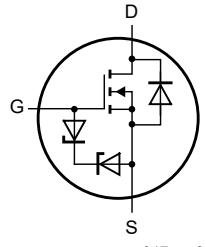
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25 \text{ }^\circ\text{C}$		-	-	60	V
V_{GS}	gate-source voltage			-20	-	20	V
I_D	drain current	$V_{GS} = 10 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$	[1]	-	-	1.6	A
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 1.6 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$			-	164	218
							$\text{m}\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm^2 .

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 TO-236AB (SOT23)	 017aaa255
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMV164ENEA	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

7. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
PMV164ENEA	HU%

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

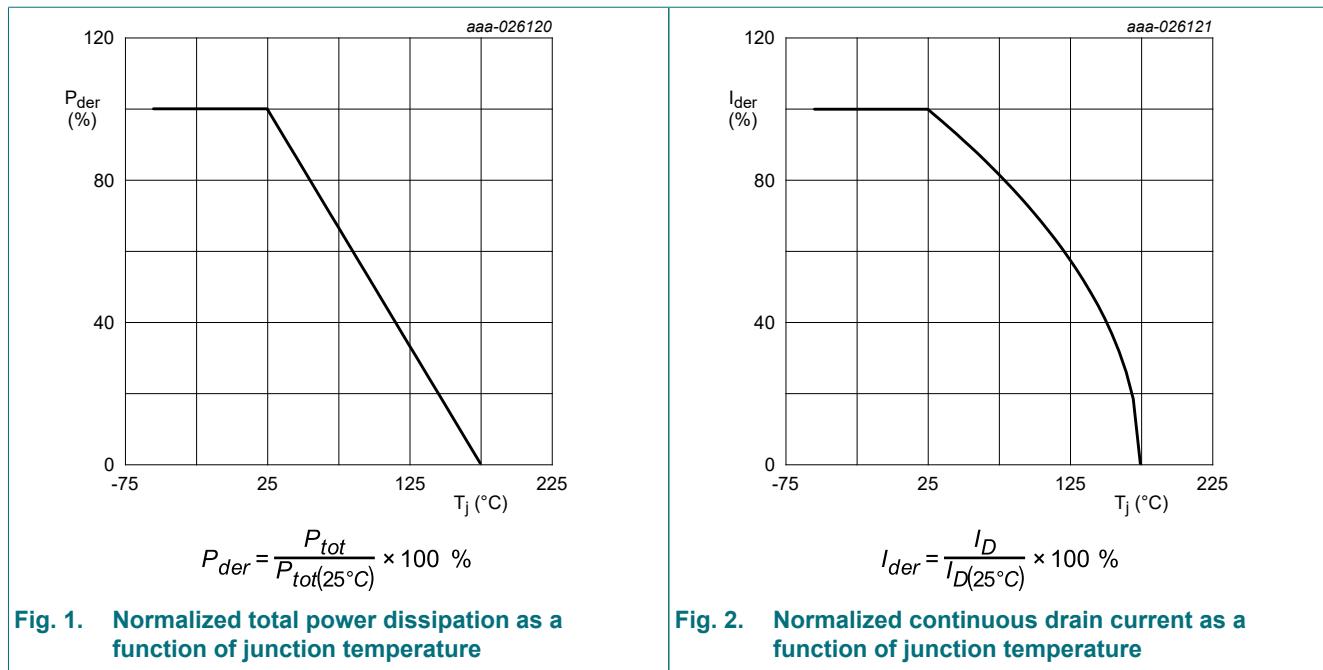
In accordance with the Absolute Maximum Rating System (IEC 60134).

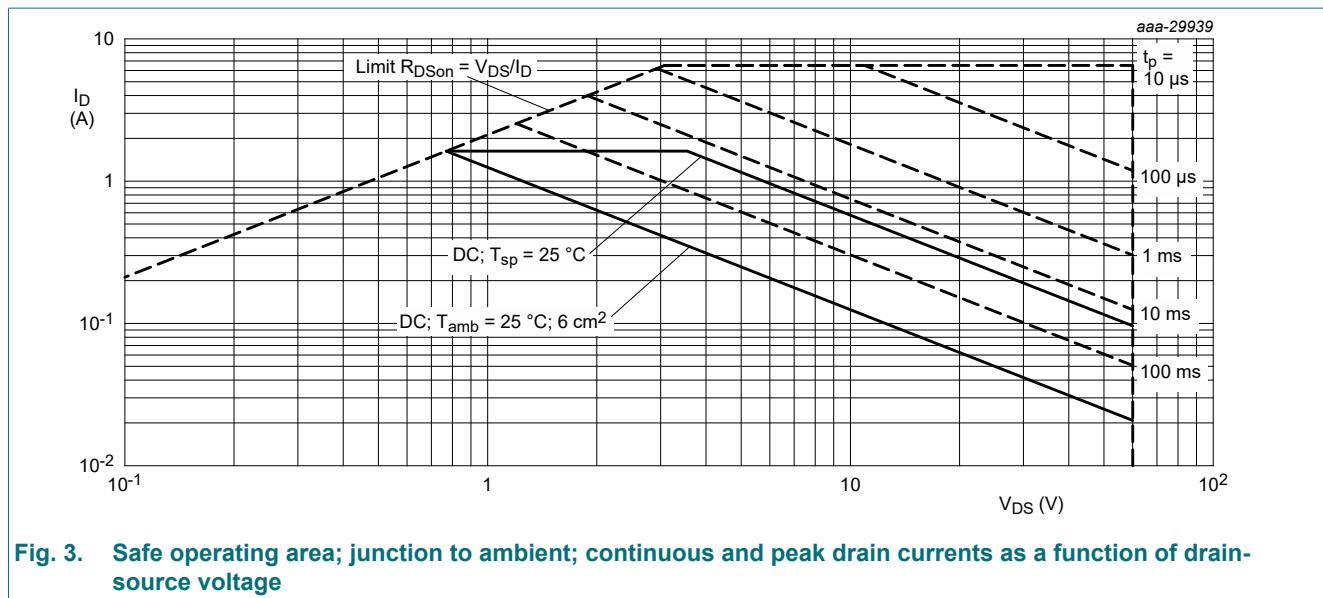
Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25^\circ\text{C}$		-	60	V
V_{GS}	gate-source voltage			-20	20	V
I_D	drain current	$V_{GS} = 10\text{ V}; T_{amb} = 25^\circ\text{C}$	[1]	-	1.6	A
		$V_{GS} = 10\text{ V}; T_{amb} = 100^\circ\text{C}$	[1]	-	1	A
I_{DM}	peak drain current	$T_{amb} = 25^\circ\text{C}$; single pulse; $t_p \leq 10\text{ }\mu\text{s}$		-	6.5	A
P_{tot}	total power dissipation	$T_{amb} = 25^\circ\text{C}$	[2]	-	640	mW
			[1]	-	1.25	W
		$T_{sp} = 25^\circ\text{C}$		-	5.8	W
T_j	junction temperature			-55	175	°C
T_{amb}	ambient temperature			-55	175	°C
T_{stg}	storage temperature			-65	175	°C
Source-drain diode						
I_S	source current	$T_{amb} = 25^\circ\text{C}$	[1]	-	1.3	A
ESD maximum rating						
V_{ESD}	electrostatic discharge voltage	HBM	[3]	-	2000	V
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$T_{j(\text{init})} = 25^\circ\text{C}; I_D = 0.17\text{ A}$; DUT in avalanche (unclamped)		-	5	mJ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.





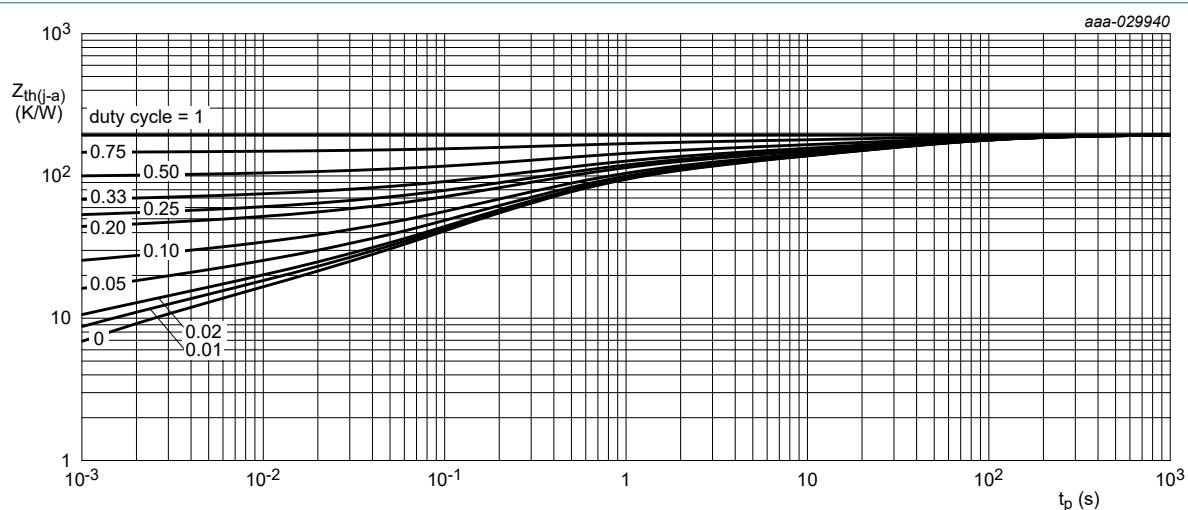
9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	195	235	K/W
			[2]	-	100	120	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	18	26	K/W

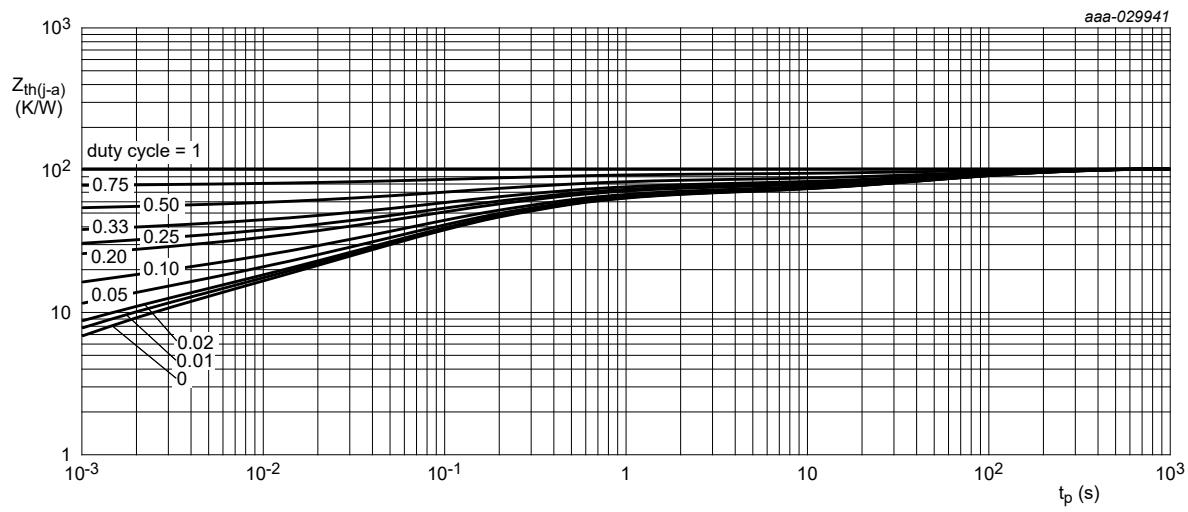
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².



FR4 PCB, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for drain 6 cm²

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25^\circ C$		60	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = 250 \mu A; V_{DS} = V_{GS}; T_j = 25^\circ C$		1.3	1.7	2.7	V
I_{DSS}	drain leakage current	$V_{DS} = 60 V; V_{GS} = 0 V; T_j = 25^\circ C$		-	-	1	μA
I_{GSS}	gate leakage current	$V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	10	μA
		$V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	-10	μA
		$V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	1	μA
		$V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25^\circ C$		-	-	-1	μA
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10 V; I_D = 1.6 A; T_j = 25^\circ C$		-	164	218	$m\Omega$
		$V_{GS} = 10 V; I_D = 1.6 A; T_j = 175^\circ C$		-	356	473	$m\Omega$
		$V_{GS} = 4.5 V; I_D = 1.5 A; T_j = 25^\circ C$		-	195	262	$m\Omega$
g_{fs}	forward transconductance	$V_{DS} = 10 V; I_D = 1.6 A; T_j = 25^\circ C$		-	4	-	S
R_G	gate resistance	$f = 1 \text{ MHz}$		-	13.2	-	Ω
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	$V_{DS} = 30 V; I_D = 1.6 A; V_{GS} = 10 V; T_j = 25^\circ C$		-	2.5	3.8	nC
Q_{GS}	gate-source charge			-	0.3	-	nC
Q_{GD}	gate-drain charge			-	0.7	-	nC
C_{iss}	input capacitance	$V_{DS} = 30 V; f = 1 \text{ MHz}; V_{GS} = 0 V; T_j = 25^\circ C$		-	110	-	pF
C_{oss}	output capacitance			-	16	-	pF
C_{rss}	reverse transfer capacitance			-	11	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 30 V; I_D = 1.6 A; V_{GS} = 10 V; R_{G(ext)} = 6 \Omega; T_j = 25^\circ C$		-	2	-	ns
t_r	rise time			-	5	-	ns
$t_{d(off)}$	turn-off delay time			-	7	-	ns
t_f	fall time			-	3	-	ns
Source-drain diode							
V_{SD}	source-drain voltage	$I_S = 1.3 A; V_{GS} = 0 V; T_j = 25^\circ C$		-	0.8	1.2	V
t_{rr}	reverse recovery time	$I_S = 0.8 A; dI_S/dt = -100 A/\mu s; V_{GS} = 0 V; V_{DS} = 30 V; T_j = 25^\circ C$		-	10	-	ns
Q_r	recovered charge			-	3	-	nC

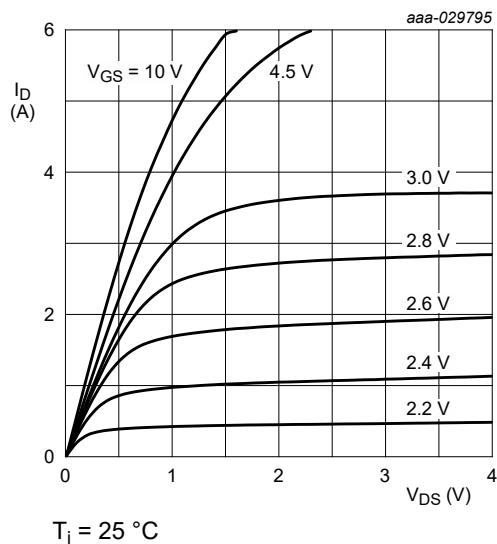


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

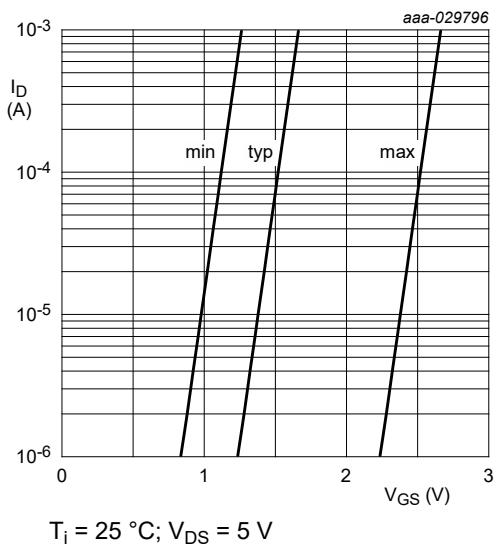


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

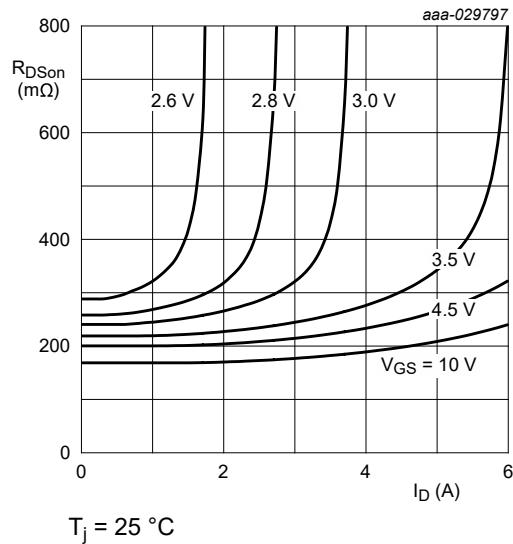


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

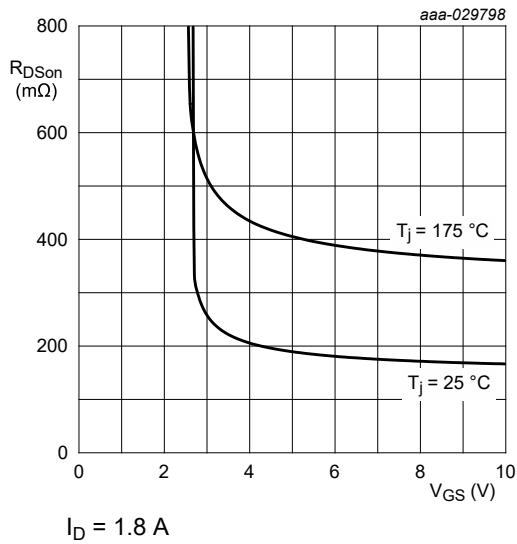


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

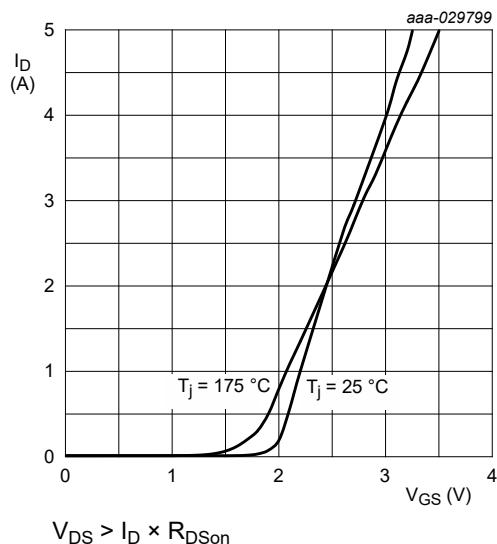


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

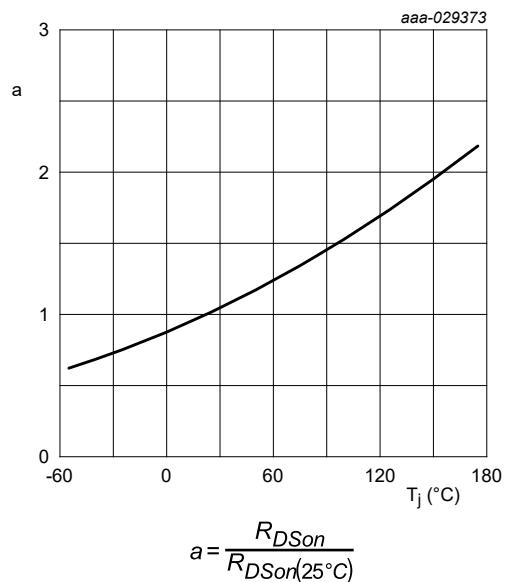


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

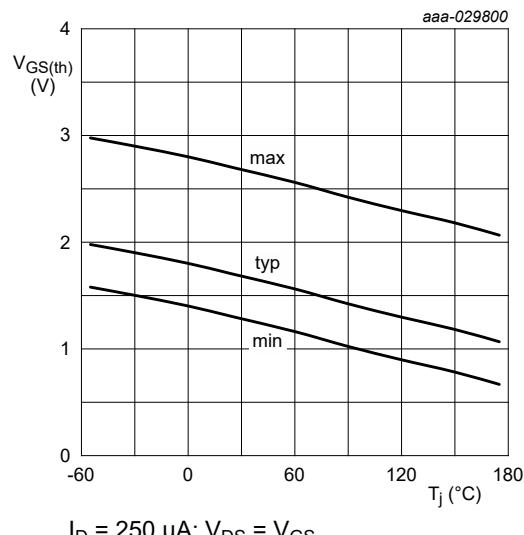


Fig. 12. Gate-source threshold voltage as a function of junction temperature

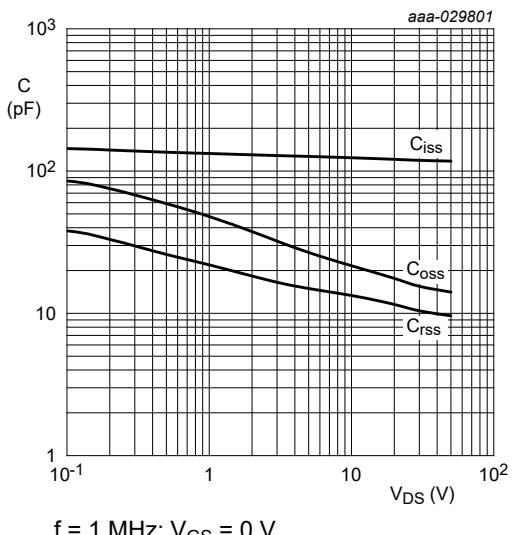
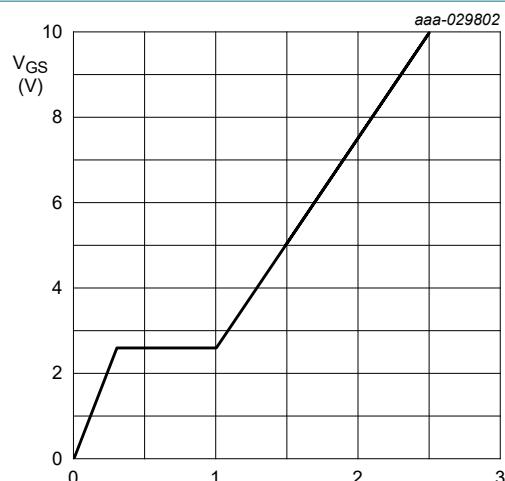


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = 1.5$ A; $V_{DS} = 30$ V; $T_{amb} = 25$ °C

Fig. 14. Gate-source voltage as a function of gate charge; typical values

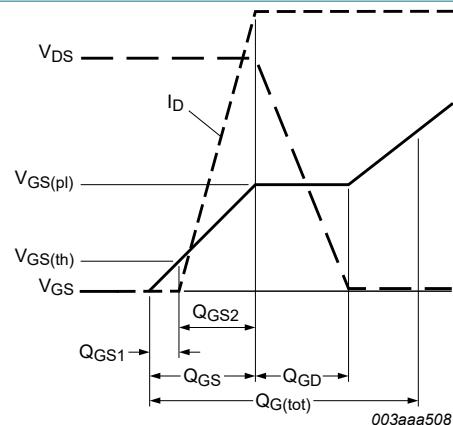
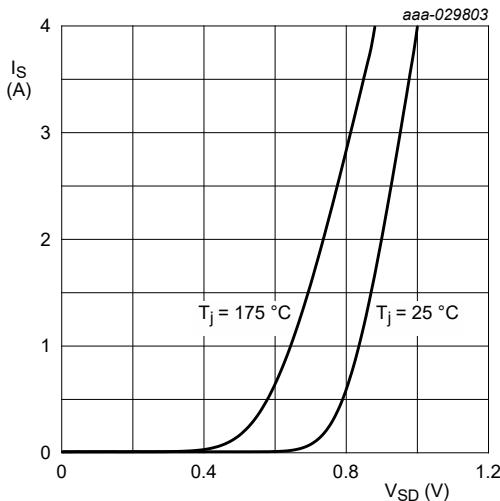


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$ V

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

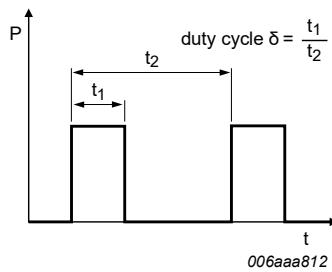
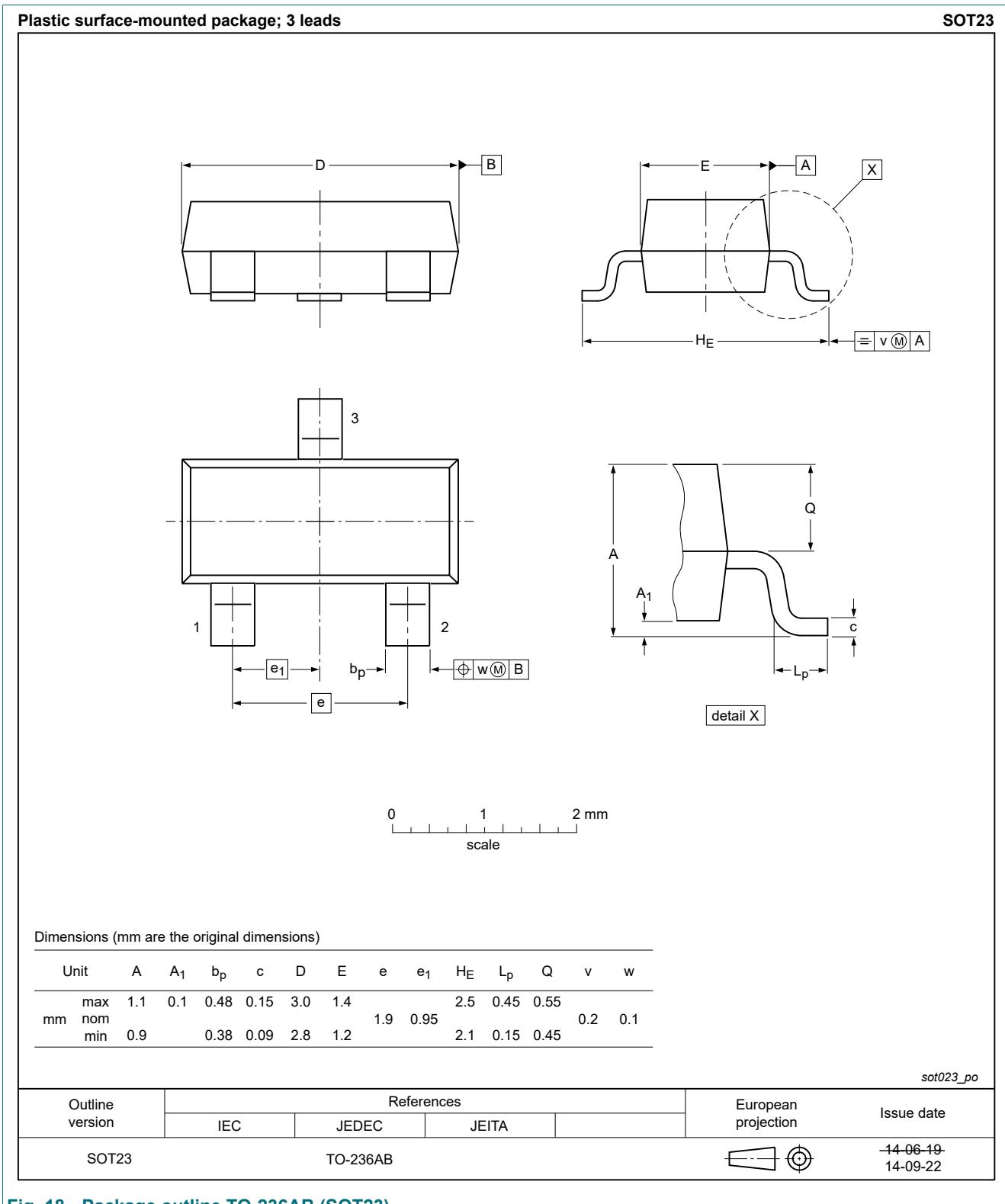


Fig. 17. Duty cycle definition

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline



13. Soldering

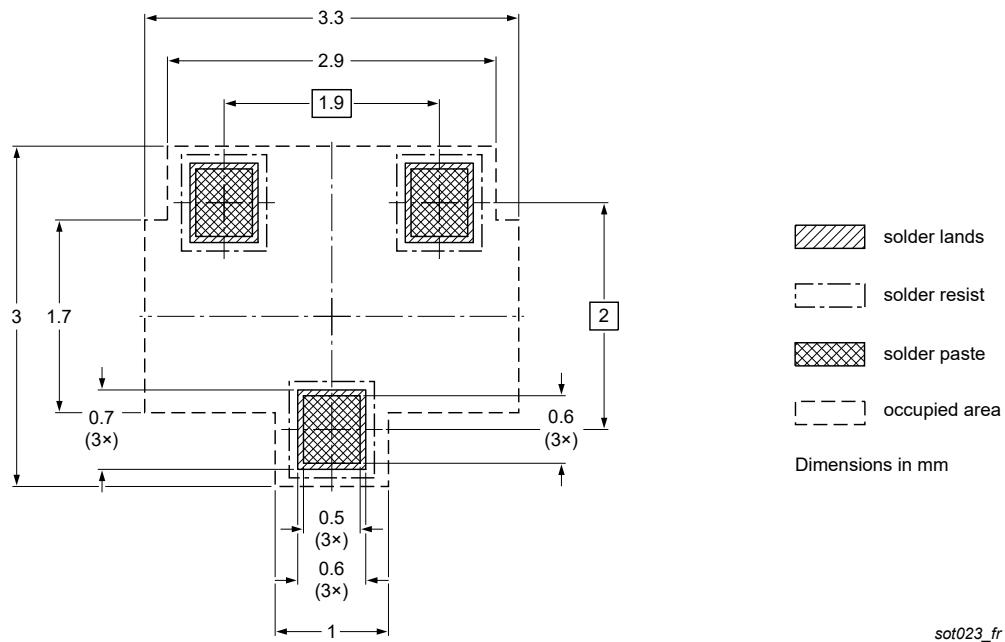


Fig. 19. Reflow soldering footprint for TO-236AB (SOT23)

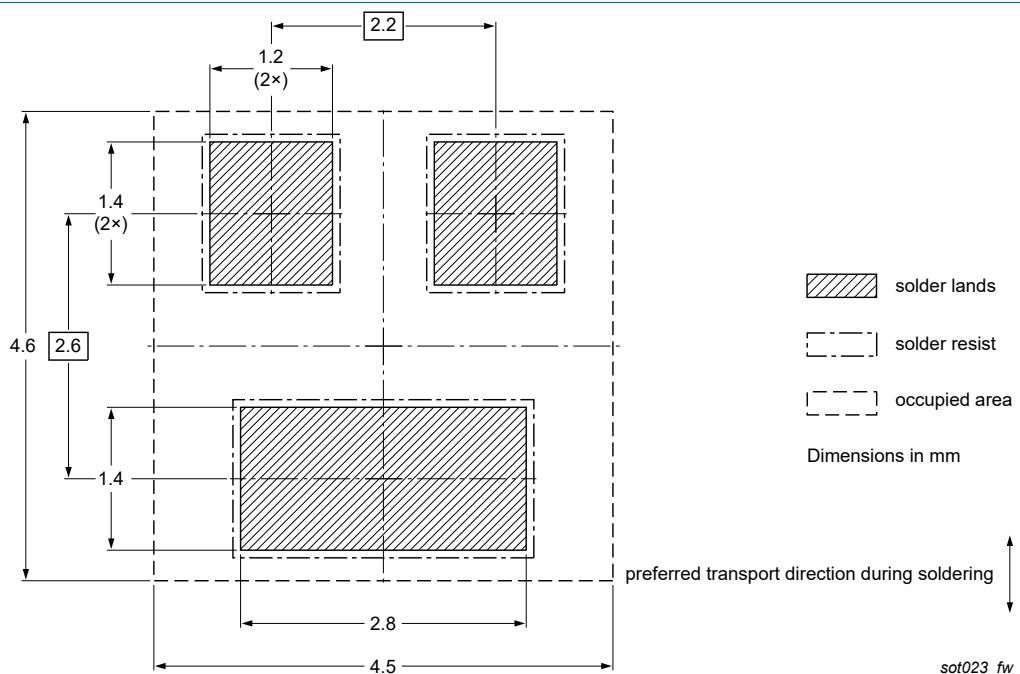


Fig. 20. Wave soldering footprint for TO-236AB (SOT23)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMV164ENEA v.1	20190507	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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Contents

1. General description.....	1
2. Features and benefits.....	1
3. Applications.....	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values.....	3
9. Thermal characteristics.....	5
10. Characteristics.....	6
11. Test information.....	10
12. Package outline.....	11
13. Soldering.....	12
14. Revision history.....	13
15. Legal information.....	14

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